

temperature control method and apparatus. To improve polished wafer flatness, a cooling fluid such as water is flowed through the workpiece. Spec. Col. 3, ll. 21-27. Walsh does not disclose or suggest using the fluid to maintain an axis of rotation of the workpiece.

Conversely, the claimed invention utilizes a fluid around an adjustable axis of rotation to "maintain a position of the axis of rotation" when desired, as recited by independent claim 18. Moreover, independent claim 46 recites "an adjustable magnetic field directed to the fluid, wherein the fluid is responsive to the adjustable magnetic field to maintain a position of an axis of rotation of the spindle." Walsh neither discloses nor suggests using a fluid in the claimed way, nor does Walsh disclose or suggest directing a magnetic field at the fluid. The remaining pending claims depend, directly or indirectly, from claim 18 or claim 46. For at least these reasons, Applicants respectfully request that the rejection to the pending claims be withdrawn.

For all of the above reasons, Applicants respectfully request reconsideration and allowance of the present application. The Examiner is invited to contact the undersigned attorney at the below-listed number if there are any outstanding issues that could be resolved through a telephone conference.

Respectfully submitted,



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